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PATENT ABSTRACTS OF JAPAN(21) Application number: **59241942**(51) Intl. Cl.: **H01L 21/58**(22) Application date: **16.11.84**

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states:(71) Applicant: **TOSHIBA CORP**(72) Inventor: **KAGINO MINORU**

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(54) DIE BONDING DEVICE

(57) Abstract:

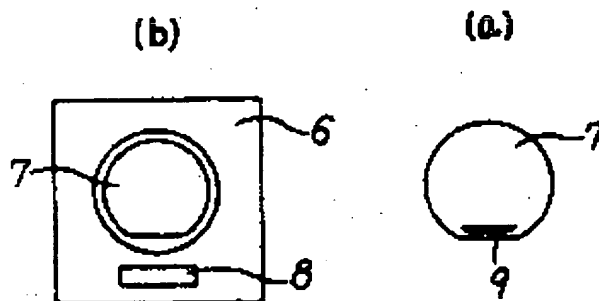
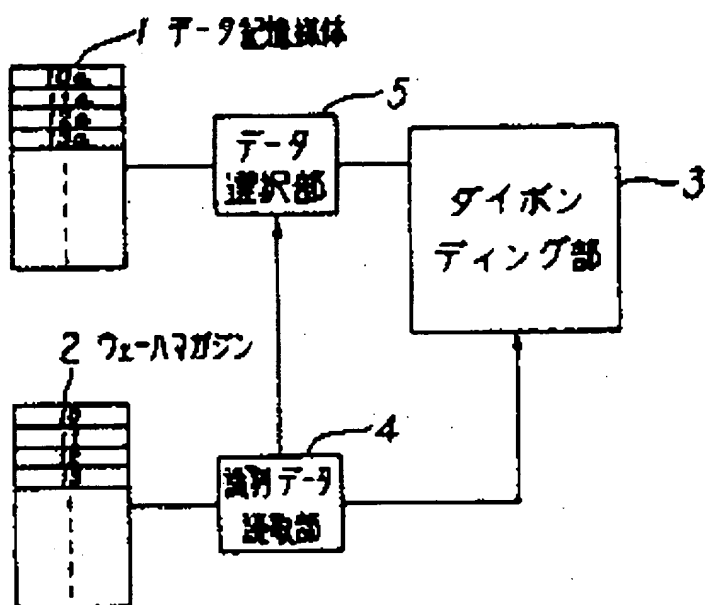
PURPOSE: To simplify the wafer handling operation between electrical testing and die bonding processes, by providing a device which can read out chip position information and quality characteristics information stored in a memory medium while recognizing the correspondence of the information with the wafer on which the information is concerned.

CONSTITUTION: Information on electric tests of each wafer is stored together with identification information as information 10a, 11a... in a memory medium 1 such as a floppy disk or the like. A wafer is taken out from a magazine 2 and identification information 9 marked on the wafer 7 or identification information 8 marked on a jig 6 is read out by an identification information reading out section 4. According to the identification information thus read, the information having the same

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identification information is selected from the memory medium 1 by a data selecting section 5 and read out. A die bonding section 3 is caused to operate according to this information. This construction can thus eliminate any possibility of becoming impossible to check the wafer even if the order of wafers is changed.

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